

L Number	Hits	Search Text	DB	Time stamp
162	4	anneal\$3 SAME copper same chemical adj polish	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:52
168	366	anneal\$3 same polish\$3 same copper	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:56
174	9	anneal\$3 same polish\$3 same copper same section	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:54
180	3	anneal\$3 same polish\$3 same copper SAME housing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:59
186	119	anneal\$3 same chemical adj polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 17:03
192	24	anneal\$3 same chemical adj polish\$3 AND copper	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 17:16
198	4	anneal\$3 same copper adj plating same chemical adj polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 17:49
204	14802	copper adj plating or electroplat\$3 near5 anneal\$3 and electrolytic or chemical adj polishing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 17:50
210	6564	(copper adj plating or electroplat\$3 near5 anneal\$3 and electrolytic or chemical adj polishing) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 17:51
216	1044	((copper adj plating or electroplat\$3 near5 anneal\$3 and electrolytic or chemical adj polishing) and substrate) and interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 17:52
222	140	((copper adj plating or electroplat\$3 near5 anneal\$3 and electrolytic or chemical adj polishing) and substrate) and interconnect) and housing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 18:21
228	171444	anneal\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 18:22
234	11648	copper adj plating	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 18:22
240	89364	electrochemical or chemical adj polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 18:24
246	116	anneal\$3 AND (copper adj plating) AND (electrochemical or chemical adj polish\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 18:51
252	8	annealing same copper adj plating same polishing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 18:56
258	4	annealing same copper adj electroplating same polishing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 18:56

	275	205/223.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:45
	15	205/223.ccls. and interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/13 18:16
	14	205/223.ccls. and interconnect and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/13 18:16
	222	anneal\$3 adj section	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:46
	0	anneal\$3 adj section SAME electropolish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:41
	0	anneal\$3 adj section SAME chemical adj polish	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:41
	1	anneal\$3 adj section SAME chemical adj polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:41
	165	anneal\$3 adj area	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:45
	6	(anneal\$3 adj area) AND (anneal\$3 adj section)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:43
	1	(anneal\$3 adj section) SAME chemical adj polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:45
	0	anneal\$3 adj area SAME electropolish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:46
	4637	anneal\$3 SAME polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:48
	1924	(anneal\$3 SAME polish\$3) and electro\$10	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:48
	16	anneal\$3 SAME electropolish\$3 SAME chemical	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:52
	1956	anneal\$3 AND 204/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:53
	38	anneal\$3 AND 204/\$.ccls. AND electropolish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:20
	55192	(anneal\$3 AND 204/\$.ccls. AND electropolish\$3) AND copper NEAR plat\$3 or electroplat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:13
	25	(anneal\$3 AND 204/\$.ccls. AND electropolish\$3) AND copper	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:13

-	786	anneal\$3 AND chemical NEAR polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:24
-	0	anneal\$3 AND electrochemical NEAR polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:23
-	55203	(anneal\$3 AND chemical NEAR polish\$3) and copper adj plat\$3 or electroplat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:28
-	23	(anneal\$3 AND chemical NEAR polish\$3) and copper adj plat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:49